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Docket No.: 501.39622X00

FORM PTO-1595
1-31-92

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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

101639327

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Masayuki SUZUKI, Kentaro Yamada, Masashi SAHARA,
Takashi NAKAJIMA, Naoki KANDA, Hidenori SUZUKI
Yoshinori MATSUMURO

3.1-01

2. Name and address of receiving party(ies):

Name: Hitachi, Ltd.

Street Address: 6, Kanda Surugadai 4-chome, Chiyoda-ku

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

City: Tokyo:

Country: Japan

Execution Date: December 26, 27, 2000; January 10, 16, 18, 2001

Additional name(s) & address(es) attached? Yes No



4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: December 26, 27, 2000; January 10, 16, 18, 2001

A. Patent Application No.(s)

B. Patent No.(s)

09/795190

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: ANTONELLI, TERRY, STOUT & KRAUS, LLP

Internal Address:

Street Address: 1300 North Seventeenth Street
Suite 1800

City: Arlington State: VA Zip: 22209

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)\$40.00

- Enclosed
- Any deficiencies may be charged to deposit account
- Authorized to be charged to deposit account

8. Deposit account number: 01-2135

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gregory E. Montone

Name of Person Signing

Attorney Registration No. 28,141

Signature

March 1, 2001

Date

Total number of pages including cover sheet, attachments, and document: 2

OMB No. 0651-0011 (exp. 4/94)

03/06/2001 00000004 09795190

03 FC:581

40.00 DP

PATENT
REEL: 011579 FRAME: 0212

ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND THE PROCESS OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Masayuki Suzuki</u> (Masayuki SUZUKI)	<u>26 / December / 2000</u>
2) <u>Kentaro Yamada</u> (Kentaro YAMADA)	<u>10 / January / 2001</u>
3) <u>Masashi Sahara</u> (Masashi SAHARA)	<u>10 / January / 2001</u>
4) <u>Takashi Nakajima</u> (Takashi NAKAJIMA)	<u>16 / January / 2001</u>
5) <u>Naoki Kanda</u> (Naoki KANDA)	<u>18 / January / 2001</u>
6) <u>Hidenori Suzuki</u> (Hidenori SUZUKI)	<u>27 / December / 2000</u>
7) <u>Yoshinori Matsumuro</u> (Yoshinori MATSUMURO)	<u>10 / January / 2001</u>
8) _____	_____
9) _____	_____
10) _____	_____